# Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment\*

### DIGI-KEY PART # ATS1022-ND

ATS PART # ATS-50290G-C2-R0

#### **Features & Benefits**

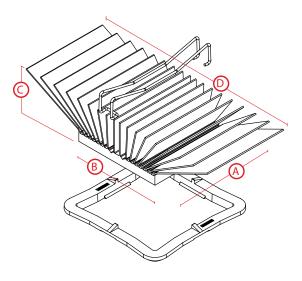
maxiFLOW<sup>™</sup> design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Designed for standard height components from 3 to 4.5mm





# Thermal Performance Table

AIR	/ELOCITY	THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED)	°C/W (DUCTED)	
200	1.0	4.5	3.7	
300	1.5	3.7		
400	2.0	3.2		
500	2.5	2.8		
600	3.0	2.6		
700	3.5	2.4		
800	4.0	2.3		

## **Product Details**<sup>†</sup>

DIMENSION A	DIMENSION B	DIMENSION C <sup>§</sup>	DIMENSION D	TIM⁺	FINISH
29	29	12.5	51.74	C1100F	BLUE-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com** 

\* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

Dimensions A & B refer to component size
Dimension C = the height of the heat sink of

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method ATS ADVANCED THERMAL SOLUTIONS, INC. Innovations in Thermal Management®



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